

**RECEIVED**  
**CENTRAL FAX CENTER**  
**MAY 16 2005**

Appn. No. 10/737,240

Filed: December 16, 2003

Applicants: Allen D. Hertz, et al.

Title: **APPLICATION OF ACOUSTIC AND VIBRATIONAL ENERGY FOR  
FABRICATING BUMPED IC DIE AND ASSEMBLY OF PCA'S**

Examiner/GAU: Lynn Edmondson/ 1725

Official Fax Number: 703-872-9306

Tel: (571) 272-1172

**Certificate of Transmission**

Certificate of Mailing: I certify that on the date below this document and referenced attachments, if any, will be transmitted via Facsimile to:

**703 872-9306**

Signed: \_\_\_\_\_

 Allen Hertz / Reg. No. 50,942

Date Transmitted: May 16, 2005

**Attachments:**

Amendment A (13 pages)

Specification – Marked Up Copy (02 Pages)

Specification – Clean Copy (02 Pages)

Certificate of Transmission (this page)

Appl. Ser. No. 10/737,240

**RECEIVED**  
**CENTRAL FAX CENTER**  
**MAY 16 2005**

Amendment A

Appn. No. 10/737,240

Filed: December 16, 2003

Applicants: Allen D. Hertz, et al.

Title: **APPLICATION OF ACOUSTIC AND VIBRATIONAL ENERGY FOR  
FABRICATING BUMPED IC DIE AND ASSEMBLY OF PCA'S**

Examiner/GAU:Lynn Edmondson/ 1725

Official Fax Number: 703-872-9306

Tel: (571) 272-1172

Mailed on: 2005, May 16

**Amendment A Under 37 C.F.R. 1.121**

Commissioner of Patents and Trademarks  
Patent and Trademark Office  
United States Department of Commerce  
P.O. Box 1450  
Alexandria, VA 22313-1450

SIR:

In response to the Office Action Mailed 2005, February 24, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Please amend the Specification, Page 20, Line 29, add the following:

FIG. 1a through 1d describes the prior art, presenting the features for screen printing solder paste, and the like, onto a printed circuit assembly, integrated circuit wafer, and the like.

FIG. 2 teaches the limitations of the prior art, describing an aspect ratio.